TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM458769

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Termination and Release of Trademark and Patent Security Agreement recorded at Reel 3875/Frame 0958 and Reel 3875/Frame 0920

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
PNC Bank, National Association		01/16/2018	National Banking Association: UNITED STATES

RECEIVING PARTY DATA

Name:	Wafer Holdings, Inc.
Street Address:	6330 Hedgewood Drive, Suite 150
City:	Allentown
State/Country:	PENNSYLVANIA
Postal Code:	18106
Entity Type:	Corporation: DELAWARE

PROPERTY NUMBERS Total: 6

Property Type	Number	Word Mark
Registration Number:	2993100	LUCID2
Registration Number:	2295797	GOLDFINGER
Registration Number:	2040148	VERTEQ
Registration Number:	2691082	AKRION
Registration Number:	1598327	SUBMICRON
Registration Number:	1574491	SUNBURST

CH $165.00 2993100

CORRESPONDENCE DATA

Fax Number: 9494754754

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	12833-00001
NAME OF SUBMITTER:	Stephanie Kann

SIGNATURE:	/stephanie kann/
DATE SIGNED:	01/19/2018

Total Attachments: 9
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TERMINATION AND RELEASE OF TRADEMARK AND PATENT SECURITY AGREEMENTS

THIS TERMINATION AND RELEASE OF TRADEMARK AND PATENT SECURITY AGREEMENTS (this "Termination"), is dated as of January 16, 2018, and made by **PNC BANK, NATIONAL ASSOCIATION** (the "Grantee"), to **WAFER HOLDINGS, INC.**, a Delaware corporation (the "Grantor").

WHEREAS, pursuant to that certain (i) Revolving Credit and Security Agreement, dated as of September 26, 2008 (as amended, restated or otherwise modified through the date hereof, the "Security Agreement"); (ii) Trademark and Patent Security Agreement, dated as of September 26, 2008 (as amended, restated or otherwise modified through the date hereof, the "Trademark and Patent Security Agreement"); (iii) Export-Import Revolving Credit and Security Agreement, dated as of September 26, 2008 (as amended, restated or otherwise modified through the date hereof, the "Ex-Im Security Agreement"); and (iv) Export-Import Trademark and Patent Security Agreement, dated as of September 26, 2008 (as amended, restated or otherwise modified through the date hereof, the "Ex-Im Trademark and Patent Security Agreement" and together with the Trademark and Patent Security Agreement, each a "Trademark and Patent Security Agreement" and collectively, the "Trademark and Patent Security Agreements"), made by Grantor in favor of Grantee a security interest was granted by the Grantor to Grantee in certain collateral, including the Trademarks and Patents (as hereinafter defined);

WHEREAS, the Trademark and Patent Security Agreement was recorded with the trademark division of the United States Patent and Trademark Office on October 24, 2008 at Reel 003875, Frame 0958, and with the patent division of the United States Patent and Trademark Office on October 27, 2008 at Reel 021744, Frame 0209;

WHEREAS, the Ex-Im Trademark and Patent Security Agreement was recorded with the trademark division of the United States Patent and Trademark Office on October 24, 2008 at Reel 003875, Frame 0920, and with the patent division of the United States Patent and Trademark Office on October 27, 2008 at Reel 021731, Frame 0608;

WHEREAS, Grantee now desires to terminate and release the Trademark and Patent Security Agreements;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which are hereby acknowledged, and upon the terms set forth in this Termination, Grantee hereby states as follows:

1. Definitions. The terms "Trademarks" and "Patents" as used herein, shall mean all of the Grantor's right, title and interest of every kind and nature as of the date hereof in the Trademarks and Patents listed on Schedule A hereto.

2. Release of Security Interest. Grantee does hereby terminate, release and discharge the entirety of any and all liens or security interests that it may have in, and all claims, whether presently existing or hereafter acquired or created, pursuant to any Trademark and Patent Security Agreement, in the Trademarks and Patents and reassigns to the person or persons legally entitled thereto all right, title and interest of Grantee in the Trademarks and Patents.

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IN WITNESS WHEREOF, the Grantee has caused this Termination to be executed by its duly authorized officer as of the date first written above.

PNC BANK, NATIONAL ASSOCIATION

By: _____
Name: James Sierakowski
Title: Senior Vice President

[Signature Page to Termination and Release]

SCHEDULE A

TRADEMARKS

LUCID2	United States of America	78/224,085	11-Mar-2003	2,993,100	06-Sep-2005
GOLDFINGER	United States of America	75/555,468	18-Sep-1998	2,295,797	30-Nov-1999
VERTEQ	United States of America	75/035,442	21-Dec-1995	2,040,148	25-Feb-1997
AKRION	United States of America	78/122,937	19-Apr-2002	2,691,082	25-Feb-2003
SUBMICRON	United States of America	73/817,473	7-Aug-1989	1,598,327	29-May-1990
SUNBURST	United States of America	73/760,371	28-Oct-1988	1,574,491	02-Jan-1990

PATENTS

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Acoustic Energy System, Method Apparatus for Processing Flat Articles	US	11/625,556	1/22/2007	8/31/2010	7,784,478
Acoustic Generating Device	US	61/034,142	3/5/2008		
Apparatus and Method for Cleaning and Drying a Hydrophobic Surface of a Substrate	US	11/755,619	5/30/2007		
Apparatus and Method for the Cleaning of Substrates	US	10/111,332	4/18/2002	11/16/2004	6,817,369
Apparatus and Method for Transmitting Energy Through a Non-Reactive Transmitter Bonded to a Transducer and Use of the Same to Process Substrates	US	11/625,651	1/22/2007		
Apparatus and Method of Measuring Acoustical Energy Applied to a Substrate	US	11/837,292	8/10/2007	11/23/2010	7,836,769
Apparatus and Methods for Vapor Generation System	US	10/098,847	3/15/2002	4/20/2004	6,722,056
Apparatus for Processing Substrates in a Fluid Tank	US	09/171,757	10/23/1998	11/14/2000	6,145,520
Apparatus, System and Method for Processing a Substrate that Prohibits Air Flow Containing Contaminants and/or Residues from Depositing on the Substrate	US	11/777,256	7/12/2007	8/2/2011	7,990,289
Capillary Drying of Substrates	US	10/358,636	2/5/2003	6/21/2005	6,907,890
Centrifugal Wafer Processor	US	90/002,139	9/14/1990	1/21/1992	4,571,850
Chemical Concentration Control Device	US	10/117,725	4/5/2002	7/27/2004	6,766,818
Cleaning and Drying Method and Apparatus	US	10/091,011	3/4/2002	1/4/2005	6,837,944
Compliant Silicon Wafer Handling System	US	08/825,883	4/2/1997	9/11/2001	6,286,688
Device and Method for Processing Substrates	US	09/869,213	9/22/2001	10/19/2004	6,805,754
Device and Method for the Treatment of Substrates in a Fluid Container	US	09/367,683	12/31/1999	11/18/2003	6,647,641
Device and Method for the Treating Substrates in a Fluid Container	US	08/862,890	5/23/1997	9/21/1999	5,954,068

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Device for Chemical Wet Treatment	US	08/875,408	7/31/1997	5/11/1999	5,902,402
Device for Treating Substrates in a Fluid Container	US	08/761,717	12/6/1996	6/5/2001	6,240,938
Device for Wet-Treatment of Substrates	US	09/171,271	6/22/1999	8/7/2001	6,269,822
Dump Door	US	10/085,565	2/26/2002	1/18/2005	6,843,859
Facility for Treating Objects in a Process Tank	US	09/068,618	7/7/1998	2/25/2003	6,523,552
Industrial Robot Safety Device That Shuts Down Operation in Response to Variation in Tension of a Rope	US	08/851,668	5/6/1997	9/15/1998	5,807,408
Low Profile Wafer Carrier	US	10/053,449	1/17/2002	3/29/2005	6,871,657
Megasonic Cleaner and Dryer System	US	10/171,430	6/12/2002	8/16/2005	6,928,751
Megasonic Cleaner and Dryer	US	10/171,429	6/12/2002	8/2/2005	6,923,192
Megasonic Cleaner and Dryer	US	10/171,426	6/12/2002	6/29/2004	6,754,980
Megasonic Cleaner and Dryer	US	10/864,927	6/10/2002	9/5/2006	7,100,304
Megasonic Cleaner Probe System with Gasified Fluid	US	09/906,384	7/16/2001	2/3/2004	6,684,890
Megasonic Cleaner Probe System with Gasified Fluid	US	10/742,214	12/19/2003	5/23/2006	7,047,989
Megasonic Cleaner Probe System with Gasified Fluid	US	10/864,929	6/10/2004	1/2/2007	7,156,111
Megasonic Cleaner Probe System with Gasified Fluid	US	11/595,029	11/9/2006	8/25/2009	7,578,302
Megasonic Cleaner System With Buffered Cavitation Method	US	10/341,425	1/10/2003	9/12/2006	7,104,268
Megasonic Cleaning System	US	08/277,792	7/20/1994	4/29/1997	5,625,249
Megasonic Cleaning System	US	07/791,094	11/12/1991	9/28/1993	5,247,954
Megasonic Probe Energy Attenuator	US	09/922,509	8/3/2001	1/20/2004	6,679,272
Megasonic Probe Energy Attenuator	US	10/760,596	1/20/2004	5/17/2005	6,892,738
Megasonic Probe Energy Director	US	10/059,682	1/29/2002	10/30/2007	7,287,537
Megasonic Probe Energy Director	US	11/873,750	10/17/2007	11/10/2009	7,614,406
Megasonic Transducer Assembly	US	08/042,889	4/5/1993	11/22/1994	5,365,960
Megazone System	US	10/117,768	4/5/2002	3/18/2003	6,532,974
Megazone System	US	10/304,583	11/25/2002	9/30/2003	6,626,189
Membrane Dryer	US	10/117,739	4/5/2002	1/18/2005	6,842,998
Membrane Dryer	US	10/951,009	9/27/2004	8/16/2005	6,928,750

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Method and Apparatus for Drying Semiconductor Wafers	US	08/275,807	7/15/1994	9/17/1996	5,556,479
Method and Apparatus for Treating Substrates	US	09/600,084	6/30/2000	8/19/2003	6,607,604
Method and System for Chemical Injection in Silicon Wafer Processing	US	10/053,364	1/18/2002	7/27/2004	6,767,877
Method and System for Processing a Substrate Using a Composite Transmitter	US	60/985,947	11/6/2007		
Method and Systems for Determining Chemical Concentrations and Controlling the Processing of Semiconductor Substrates	US	09/257,488	2/25/1999	7/17/2001	6,261,845
Method for Cavitation Measurement	US	61/031,845	2/27/2008		
Method for Post-CMP Advanced Front End of Line Cleaning	US	12/070,620	2/19/2008	6/3/2014	8,741,066
Methods for Treating Semiconductor Wafers	US	09/096,898	6/12/1998	10/26/1999	5,972,123
Nextgen Wet Process Tank	US	10/117,778	4/5/2002	1/11/2005	6,840,250
Nozzle for Use in the Megasonic Cleaning of Substrates	US	11/781,835	7/23/2007	5/10/2011	7,938,131
Process and Apparatus for Removal of Photoresist from Semiconductor Wafers Using Spray Nozzles	US	10/366,054	2/13/2003	11/16/2004	6,818,563
Process for Etching Oxide Films in a Sealed Photochemical Reactor	US	07/876,043	4/30/1992	8/10/1993	5,234,540
Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing	US	10/909,764	8/2/2004	1/30/2007	7,169,253
Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing	US	11/649,535	1/4/2007		
Reciprocating Megasonic Probe	US	10/140,029	5/6/2002	3/6/2007	7,185,661
Reciprocating Megasonic Probe	US	11/640,718	12/18/2006		
Semiconductor Wafer Cleaning System	US	08/361,139	12/21/1994	8/12/1997	5,656,097

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Semiconductor Wafer Cleaning System	US	08/908,330	8/7/1997	6/1/1999	5,908,509
Semiconductor Wafer Cleaning System	US	08/908,345	8/7/1997	12/7/1999	5,996,595
Semiconductor Wafer Cleaning System	US	08/910,033	8/11/1997	9/14/1999	5,950,645
Semiconductor Wafer Cleaning System	US	09/694,938	10/23/2000	4/30/2002	6,378,534
Single Chamber Megasonic Energy Center	US	07/598,909	10/16/1990	9/22/1992	5,148,823
Single Wafer Megasonic Semiconductor Wafer Processing System	US	07/598,426	10/16/1990	2/25/1992	5,090,432
Single Wafer Megasonic Semiconductor Wafer Processing System	US	07/809,799	12/18/1991	2/15/1994	5,286,657
Spray let Cleaning Apparatus and Method	US	11/745,866	5/8/2007	5/24/2011	7,946,299
Substrate Process Tank with Acoustical Source Transmission and Method of Processing Substrate	US	10/699,042	10/31/2003	10/18/2005	6,955,727
Substrate Processing Device	US	09/308,850	5/24/1999	2/20/2001	6,189,552
System and Method for Drying a Rotating Substrate	US	11/624,445	1/18/2007	1/12/2010	7,644,512
System and Method for Point-of-Use Filtration and Purification of Fluids Used in Substrate Processing	US	10/895,511	7/20/2004	12/25/2007	7,311,847
System and Method for Processing a Substrate Utilizing a Gas Stream for Particle Removal	US	11/841,427	8/20/2007		
System and Method for Selective Etching a Silicon Nitride During Substrate Processing	US	10/585,229	4/20/2007		
System and Method of Cleaning Substrates Using a Subambient Process Solution	US	11/544,802	10/6/2006		
System and Method of Determining the Operating Frequency at Which to power a Transducer	US	12/059,602	3/31/2008		
System and Method of Processing Substrates Using Sonic Energy Having Cavitation Control	US	11/454,447	6/15/2006		
System for Removal of Photoresist Using Sparger	US	10/052,823	1/17/2002	11/18/2003	6,649,018

Title	Country	Application Number	Application Date	Issue Date	Patent Number
System for Removal of Photoresist Using Sparger	US	10/634,440	8/5/2003	3/8/2005	6,863,836
Transducer Assembly Incorporating a Transmitter Having Through Holes, and Method and System for Cleaning a Substrate Utilizing the Same	US	11/777,252	7/12/2007		
Vapor Drying System and Method	US	09/227,637	1/8/1999	12/11/2001	6,328,809
Vapor Jet Dryer Apparatus and Method	US	07/837,221	2/18/1992	7/13/1993	5,226,242
Wafer Cleaning System	US	08/724,518	9/30/1996	3/21/2000	6,039,059
Wafer Cleaning System	US	09/057,182	4/8/1998	10/31/2000	6,140,744
Wafer Cleaning System	US	09/953,504	9/13/2001	10/15/2002	6,463,938
Wafer Cleaning System	US	10/243,463	9/12/2002	1/27/2004	6,681,782
Wafer Cleaning System	US	10/243,486	9/12/2002	2/3/2004	6,684,891
Wafer Cleaning System	US	10/726,774	12/3/2003	10/10/2006	7,117,876
Wafer Cleaning System	US	11/375,907	3/15/2006	9/11/2007	7,268,469
Wafer Cleaning System	US	11/386,634	3/22/2006	5/1/2007	7,211,932
Wafer Cleaning System	US	11/839,885	8/16/2007	4/14/2009	7,518,288
Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	US	09/324,813	6/21/1999	6/12/2001	6,245,158